



OG02C

2-megapixel product brief

New 3.45-micron BSI Global Shutter Image Sensor for Machine Vision Applications

The new OG02C10/1B Global Shutter (GS) image sensor features a 3.45-micron (μm) back-side illuminated (BSI) pixel for high sensitivity, industry-leading shutter efficiency and excellent low-light performance for applications including industrial automation, robotics, logistics, and barcode scanners. The advanced performance in a smaller pixel enables it to replace larger 4.8 μm pixel front-side illuminated (FSI) sensors traditionally used in machine vision products.

The OG02C10/1B is a 2-megapixel BSI GS sensor that features OMNIVISION's industry-leading technology including Nyxel® near-infrared (NIR) and PureCel®Plus-S. It comes in a

1/2.53-inch optical format (OF) and supports 300 frames per second (fps) with 106 dB shutter efficiency. 20Ke- full-well capacity (FWC) enables higher high dynamic range (HDR) with low noise level, resulting in clearer pictures. On-chip dual conversion gain (DCG™) HDR extends dynamic range, reproducing motion artifact-free and low-noise images in challenging lighting conditions.

The GS sensor fits the standard C-mount and S-mount lens and supports both LVDS and MIPI interfaces.

Find out more at www.ovt.com.



- OG02C10-A88A-001A-Z (color, lead-free)
88-pin CSP
- OG02C1B-A88A-001A-Z (b&w, lead-free)
88-pin CSP

Applications

- factory automation (FA)
- machine vision camera
- industrial bar code scanning
- robotics

Technical Specifications

- active array size:** 1632 x 1264
- maximum image transfer rate:**
 - full size:
 - 300 fps @ 8-bit
 - 240 fps @ 10-bit
 - 180 fps @ 12-bit
 - DCG™ HDR mode:
 - 120 fps @ 12-bit
- power supply:**
 - analog: 2.8V
 - digital: 1.2V
 - I/O pads: 1.8V
- output formats:** 10-bit/12-bit RAW
- temperature range:**
 - operating: -30°C to +85°C junction temperature
 - stable image: 0°C to +70°C junction temperature
- output interfaces:** 1/2/4/8-lane LVDS, 4-lane MIPI
- lens size:** 1/2.53"
- lens chief ray angle:** 8° linear
- pixel size:** 3.45 μm x 3.45 μm
- image area:** 5685.6 μm x 4416 μm

Product Features

- 3.45 μm, high sensitivity, PureCel®Plus-S, Global Shutter pixel with dual conversion gain (DCG™) and enhanced NIR QE (Nyxel®)
- on-sensor DCG™ high dynamic range (HDR)
- dual exposure readout, with external trigger mode
- horizontal/vertical 2x2 sub-sampling
- supports ROI read out modes up to 8x8 windows
- embedded frame counter feature
- dynamic defective pixel cancellation (DPC) and OTP DPC
- automatic black level correction
- up to 8-channel sub-LVDS high speed serial interface
- SCCB for register programming
- SPI for register (0x0000-0x7FFF) programming
- external frame synchronization capability
- embedded temperature sensor
- one-time programmable (OTP) memory
- 12-bit A/D converter

Functional Block Diagram

